

阅读申明

- 1.本站收集的数据手册和产品资料都来自互联网，版权归原作者所有。如读者和版权方有任何异议请及时告之，我们将妥善解决。
- 2.本站提供的中文数据手册是英文数据手册的中文翻译，其目的是协助用户阅读，该译文无法自动跟随原稿更新，同时也可能存在翻译上的不当。建议读者以英文原稿为参考以便获得更精准的信息。
- 3.本站提供的产品资料，来自厂商的技术支持或者使用者的心得体会等，其内容可能存在描述上的差异，建议读者做出适当判断。
- 4.如需与我们联系，请发邮件到marketing@iczoom.com，主题请标有“数据手册”字样。

Read Statement

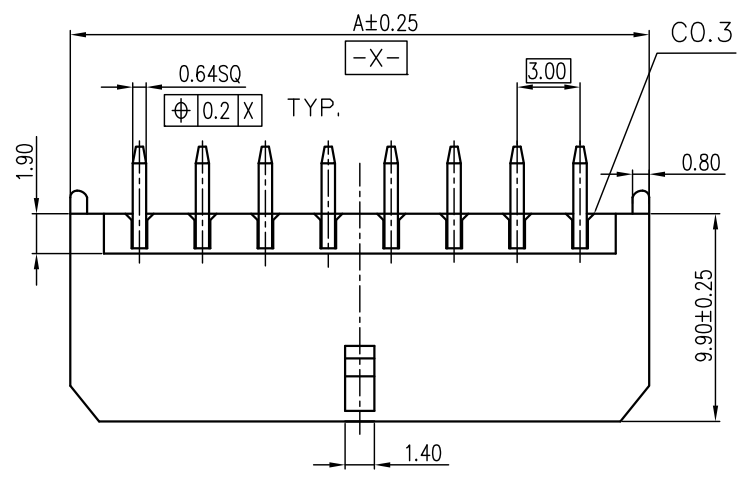
1. The datasheets and other product information on the site are all from network reference or other public materials, and the copyright belongs to the original author and original published source. If readers and copyright owners have any objections, please contact us and we will deal with it in a timely manner.
2. The Chinese datasheets provided on the website is a Chinese translation of the English datasheets. Its purpose is for reader's learning exchange only and do not involve commercial purposes. The translation cannot be automatically updated with the original manuscript, and there may also be improper translations. Readers are advised to use the English manuscript as a reference for more accurate information.
3. All product information provided on the website refer to solutions from manufacturers' technical support or users the contents may have differences in description, and readers are advised to take the original article as the standard.
4. If you have any questions, please contact us at marketing@iczoom.com and mark the subject with "Datasheets" .

This document is the property of Amphenol Corporation and is delivered on the express condition that it is not to be disclosed, reproduced or used, in whole or in part, for manufacture or sale by anyone other than Amphenol Corporation without its prior consent, and that no right is granted to disclose or to use any information in this document.

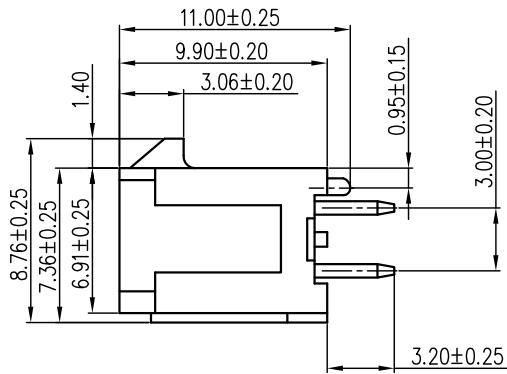
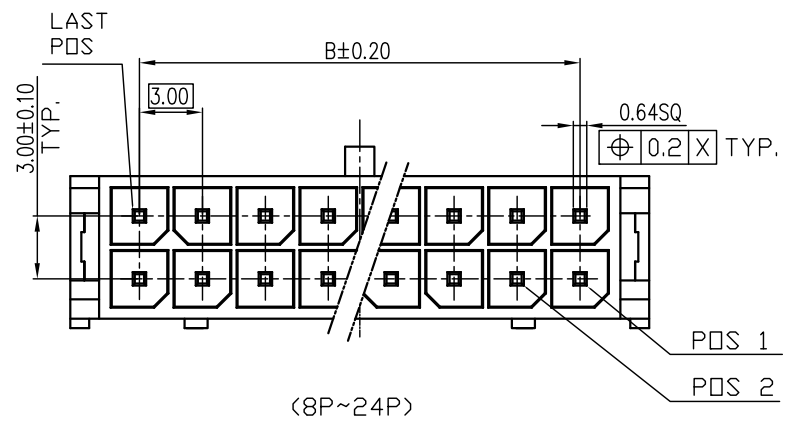
The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2011/65/EU for RoHS compliant.

**PRELIMINARY RELEASE
SUBJECT TO CHANGE**

| REVISIONS | | | | |
|-----------|----------|---|------------|-----------|
| SYM | ECN No. | DESCRIPTION | DATE | APPROVED |
| A | NE-12149 | RELEASE FOR RoHS | 08/16/2012 | Arron Lin |
| B | NE-13034 | MODIFY PLATING TO OVERALL | 03/13/2013 | Arron Lin |
| CX1 | | UPDATE FOR 2 POS., PACKING QUANTITY AND PLATING | 03/03/2014 | Arron Lin |



- NOTE:
- INSULATOR: HIGH TEMP. THERMOPLASTIC, LCP, UL 94V-0, COLOR: BLACK.
 - CONTACT MATERIAL: COPPER ALLOY;
 - FINISH:
CONTACT AREA: SELECTIVE PLATING OPTIONS;
SOLDERING AREA: MATTE TIN PLATING 100 μ" MIN OR GOLD PLATING;
UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN. OVERALL.
 - THIS PRODUCT DOESN'T ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2011/65/EU FOR RoHS.
 - APPLICABLE P.C.BOARD THICKNESS: 1.60mm
 - PACKING MUST BE PER Amphenol PACKING SPECIFICATION



| | | |
|----------------|-------|-------|
| 24 | 39.60 | 33.00 |
| 22 | 36.60 | 30.00 |
| 20 | 33.60 | 27.00 |
| 18 | 30.60 | 24.00 |
| 16 | 27.60 | 21.00 |
| 14 | 24.60 | 18.00 |
| 12 | 21.60 | 15.00 |
| 10 | 18.60 | 12.00 |
| 08 | 15.60 | 9.00 |
| 06 | 12.60 | 6.00 |
| 04 | 9.60 | 3.00 |
| 02 | 6.60 | NA |
| NO. OF CIRCUIT | A | B |

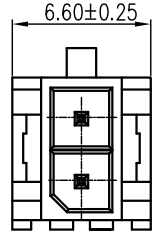
PART NO. G881AXX1X2T3EU
No. OF CIRCUIT

- CONTACT FINISH
- 0: Tin (OVERALL)
 - 1: FLASH GOLD (OVERALL)
 - 2: 15 μ" GOLD
 - 3: 30 μ" GOLD

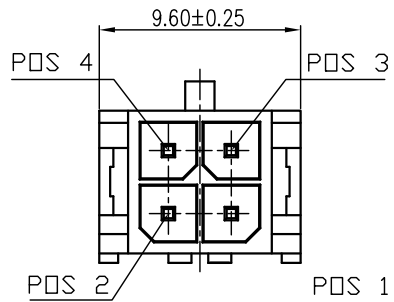
| TOLERANCE | APPROVALS | DATE | TITLE | | PART No. | | |
|----------------------------|--------------------|------------------|--|--------------|--|--|--|
| X. ±0.30 | DRAWN Debby Hung | 03/03/2014 | G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT DIP, W/O KINK | | Amphenol ® Amphenol Corporation Amphenol Taiwan Corporation | | |
| X.XX ±0.20 | CHECKED Roger Tsai | 03/03/2014 | | | | | |
| X.XXX ±0.10 | APPROVED Arron Lin | 03/03/2014 | | | | | |
| ANGULAR ±1° | DWG TYPE CUST DWG | PROJECT CODE PHD | UNIT mm | SIZE A3 | PART No. G881AXX1X2T3EU | | |
| UNLESS OTHERWISE SPECIFIED | | | SCALE NA | SHEET 1 OF 3 | DWG No. G881AXX1X2T3EU REV. CX1 | | |

This document is the property of Amphenol Corporation and is delivered on the express condition that is not to be disclosed, reproduced or used, in whole or in part, for manufacture or sale by anyone other than Amphenol Corporation without its prior consent, and that no right is granted to disclose or to use any information in this document.
 The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2011/65/EU for RoHS compliant.

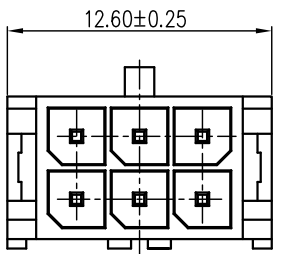
| REVISIONS | | | | |
|-----------|----------|---|------------|-----------|
| SYM | ECN No. | DESCRIPTION | DATE | APPROVED |
| A | NE-12149 | RELEASE FOR RoHS | 08/16/2012 | Arron Lin |
| B | NE-13034 | MODIFY PLATING TO OVERALL | 03/13/2013 | Arron Lin |
| CX1 | | UPDATE FOR 2 POS., PACKING QUANTITY AND PLATING | 03/03/2014 | Arron Lin |



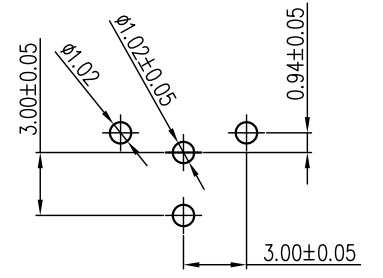
(2X1POS)



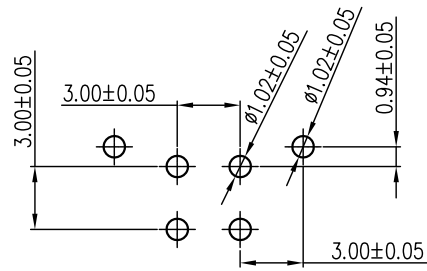
(2X2POS)



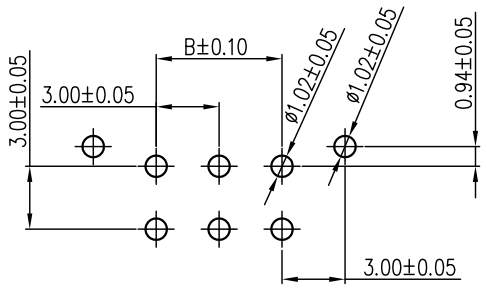
(2X3POS)



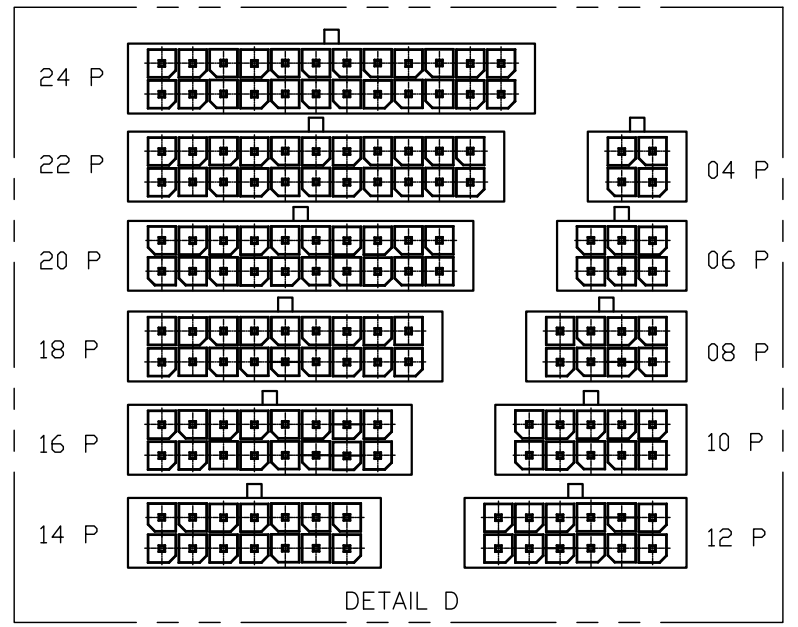
2X1 POSITIONS
RECOMMENDED PCB LAYOUT



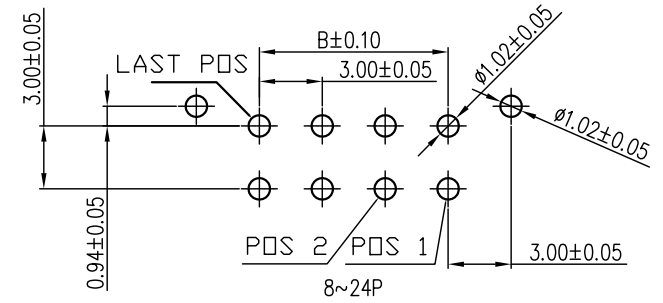
2X2 POSITIONS
RECOMMENDED PCB LAYOUT



2X3 POSITIONS
RECOMMENDED PCB LAYOUT



DETAIL D



8~24P
RECOMMENDED PCB LAYOUT

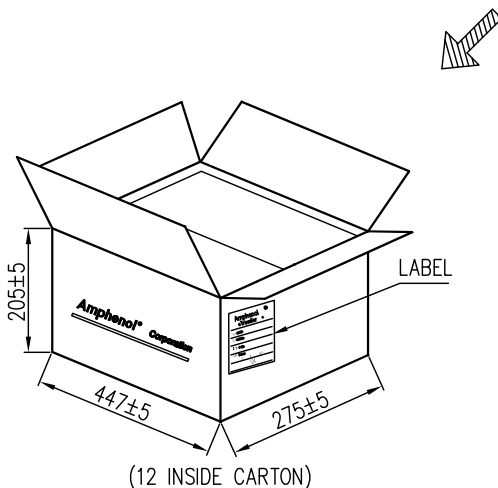
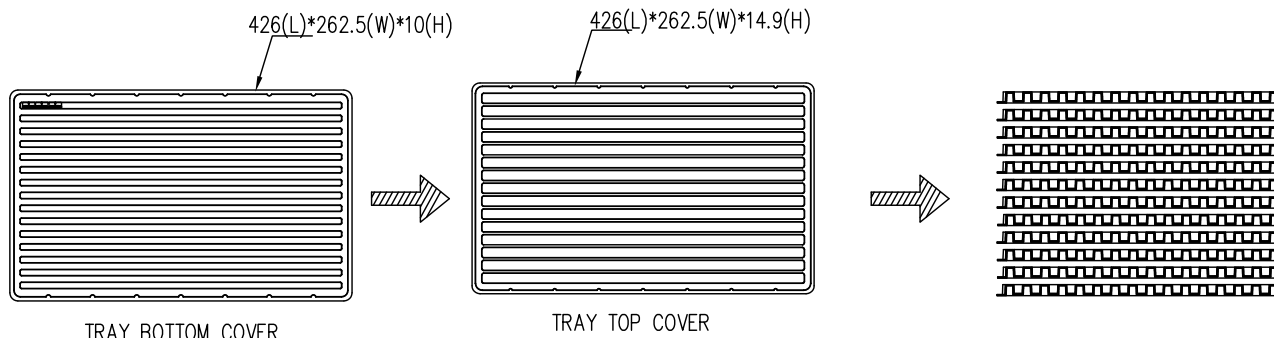
**PRELIMINARY RELEASE
SUBJECT TO CHANGE**

| TOLERANCE | | APPROVALS | | DATE | TITLE | | Amphenol® | | | | |
|----------------------------|-------|-----------|------------|--------------|--|-------|---|-------|--------|----------|----------------|
| X. | | DRAWN | Debby Hung | 03/03/2014 | G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT DIP, W/O KINK | | Amphenol Corporation Amphenol Taiwan Corporation | | | | |
| X.X | ±0.30 | CHECKED | Roger Tsai | 03/03/2014 | | | | | | | |
| X.XX | ±0.20 | APPROVED | Arron Lin | 03/03/2014 | | | | | | | |
| X.XXX | ±0.10 | DWG TYPE | CUST DWG | PROJECT CODE | PHD | UNIT | mm | SIZE | A3 | PART No. | G881AXX1X2T3EU |
| ANGULAR | ±1° | | | | | SCALE | NA | SHEET | 2 OF 3 | DWG No. | G881AXX1X2T3EU |
| UNLESS OTHERWISE SPECIFIED | | | | | | | | | | REV. | CX1 |

This document is the property of Amphenol Corporation and is delivered on the express condition that is not to be disclosed, reproduced or used, in whole or in part, for manufacture or sale by anyone other than Amphenol Corporation without its prior consent, and that no right is granted to disclose or to use any information in this document.
 The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2011/65/EU for RoHS compliant.

| REVISIONS | | | | |
|-----------|----------|---|------------|-----------|
| SYM | ECN No. | DESCRIPTION | DATE | APPROVED |
| A | NE-12149 | RELEASE FOR RoHS | 08/16/2012 | Arron Lin |
| B | NE-13034 | MODIFY PLATING TO OVERALL | 03/13/2013 | Arron Lin |
| CX1 | | UPDATE FOR 2 POS., PACKING QUANTITY AND PLATING | 03/03/2014 | Arron Lin |

**PRELIMINARY RELEASE
SUBJECT TO CHANGE**



| POS | PCS/TRAY | PCS/CARTON |
|-----|----------|------------|
| 02 | 900 | 10800 |
| 04 | 615 | 7380 |
| 06 | 465 | 5580 |
| 08 | 375 | 4500 |
| 10 | 315 | 3780 |
| 12 | 270 | 3240 |
| 14 | 240 | 2880 |
| 16 | 210 | 2520 |
| 18 | 180 | 2160 |
| 20 | 165 | 1980 |
| 22 | 150 | 1800 |
| 24 | 150 | 1800 |

NOTE:
 1. MATERIAL : BLACK CONDUCTIVE POLYSTYRENE ALLOY
 2. ALL DIMENSIONS MEET EIA-481-C REQUIREMENTS.
 3. THICKNESS : 0.80±0.05mm.

| TOLERANCE | APPROVALS | DATE | TITLE | | Amphenol [®] Amphenol Corporation Amphenol Taiwan Corporation | | |
|----------------------------|--------------------|------------------|--|--------|--|----------|----------------|
| X. ±0.30 | DRAWN Debby Hung | 03/03/2014 | G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT DIP, W/O KINK | | UNIT | SIZE | PART No. |
| X.X ±0.20 | CHECKED Roger Tsai | 03/03/2014 | | | mm | A3 | G881AXX1X2T3EU |
| X.XXX ±0.10 | APPROVED Arron Lin | 03/03/2014 | | | SCALE | SHEET | DWG No. |
| ANGULAR ±1° | DWG TYPE CUST DWG | PROJECT CODE PHD | NA | 3 OF 3 | G881AXX1X2T3EU | REV. CX1 | |
| UNLESS OTHERWISE SPECIFIED | | | | | | | |